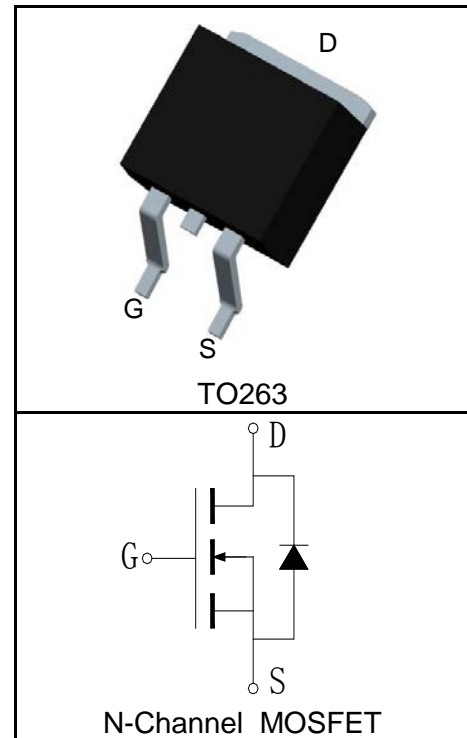


**Features**

- 40V/120A,  
 $R_{DS(ON)} = 3.5m\Omega(Typ.)@V_{GS}=10V$
- Super High Dense Cell Design
- Ultra Low On-Resistance
- 100% avalanche tested
- Lead Free and Green Devices Available (RoHS Compliant)

**Applications**

- DC-DC Converters

**Pin Description**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b> ( $T_C=25^\circ C$ Unless Otherwise Noted)			
$V_{DSS}$	Drain-Source Voltage	40	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$T_J$	Maximum Junction Temperature	175	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ C$
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ C$ 120	A
<b>Mounted on Large Heat Sink</b>			
$I_{DP}^{①}$	300 $\mu s$ Pulse Drain Current Tested	$T_C=25^\circ C$ 480	A
$I_D^{②}$	Continuous Drain Current( $V_{GS}=10V$ )	$T_C=25^\circ C$ 120	A
		$T_C=100^\circ C$ 103	
$P_D$	Maximum Power Dissipation	$T_C=25^\circ C$ 150	W
		$T_C=100^\circ C$ 75	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62.5	$^\circ C/W$
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}^{③}$	Avalanche Energy, Single Pulsed	400	mJ

**Electrical Characteristics** ( $T_C=25^{\circ}\text{C}$  Unless Otherwise Noted)

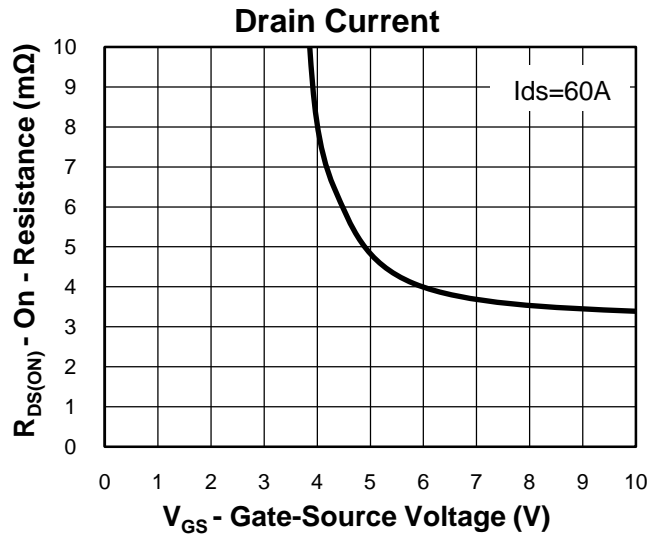
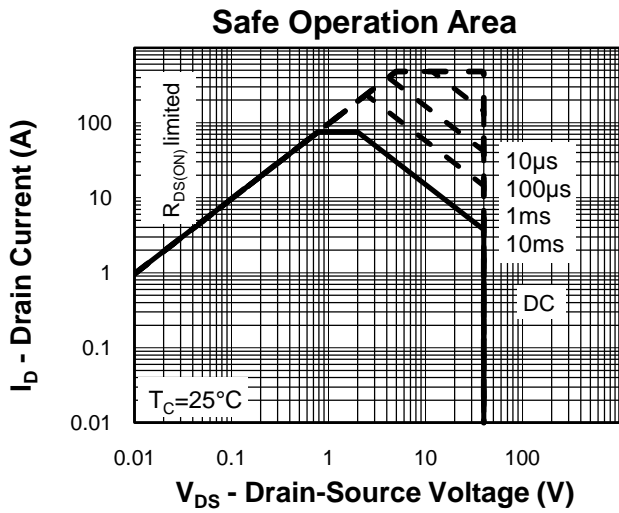
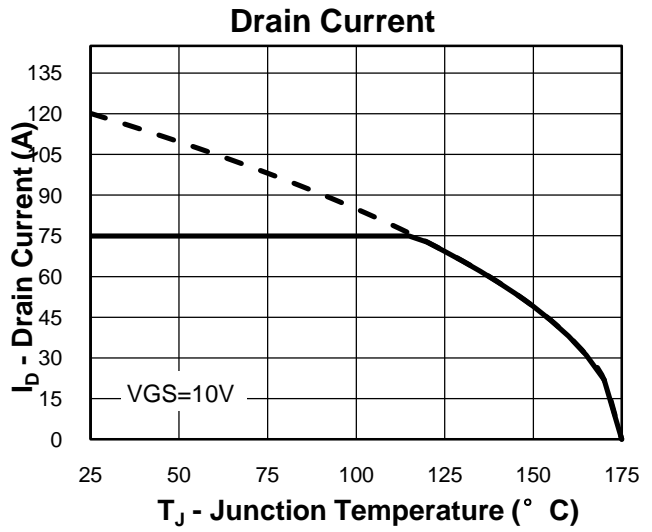
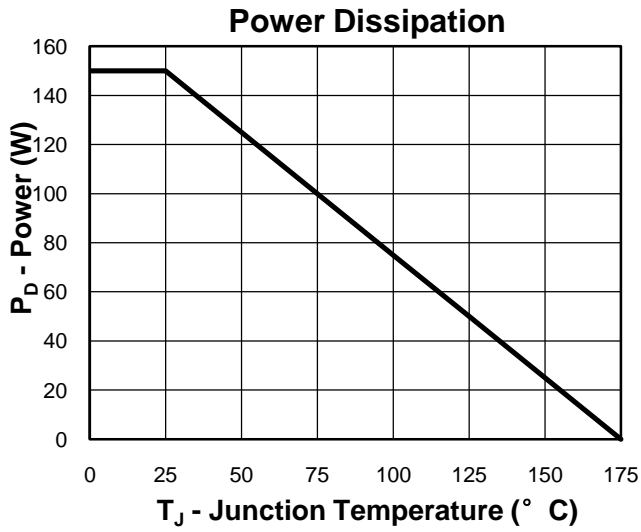
Symbol	Parameter	Test Condition	RU40120S			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	40			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=40V, V_{GS}=0V$			1	$\mu A$
		$T_J=125^{\circ}\text{C}$			30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	2		4	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$R_{DS(ON)}^{(4)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=60A$		3.5	4.5	m $\Omega$
<b>Diode Characteristics</b>						
$V_{SD}^{(4)}$	Diode Forward Voltage	$I_{SD}=60A, V_{GS}=0V$			1.2	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=60A, di_{SD}/dt=100A/\mu s$		33		ns
$Q_{rr}$	Reverse Recovery Charge			30		nC
<b>Dynamic Characteristics</b> <sup>(5)</sup>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		1.8		$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=20V, \text{Frequency}=1.0\text{MHz}$		3700		pF
$C_{oss}$	Output Capacitance			680		
$C_{riss}$	Reverse Transfer Capacitance			345		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=20V, I_{DS}=60A, V_{GEN}=10V, R_G=4.7\Omega$		36		ns
$t_r$	Turn-on Rise Time			205		
$t_{d(OFF)}$	Turn-off Delay Time			85		
$t_f$	Turn-off Fall Time			45		
<b>Gate Charge Characteristics</b> <sup>(5)</sup>						
$Q_g$	Total Gate Charge	$V_{DS}=32V, V_{GS}=10V, I_{DS}=60A$		90		nC
$Q_{gs}$	Gate-Source Charge			32		
$Q_{gd}$	Gate-Drain Charge			37		

- Notes:
- ① Pulse width limited by safe operating area.
  - ② Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 75A.
  - ③ Limited by  $T_{Jmax}$ ,  $I_{AS}=40A, V_{DD}=32V, R_G=50\Omega$ , Starting  $T_J=25^{\circ}\text{C}$ .
  - ④ Pulse test; Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
  - ⑤ Guaranteed by design, not subject to production testing.

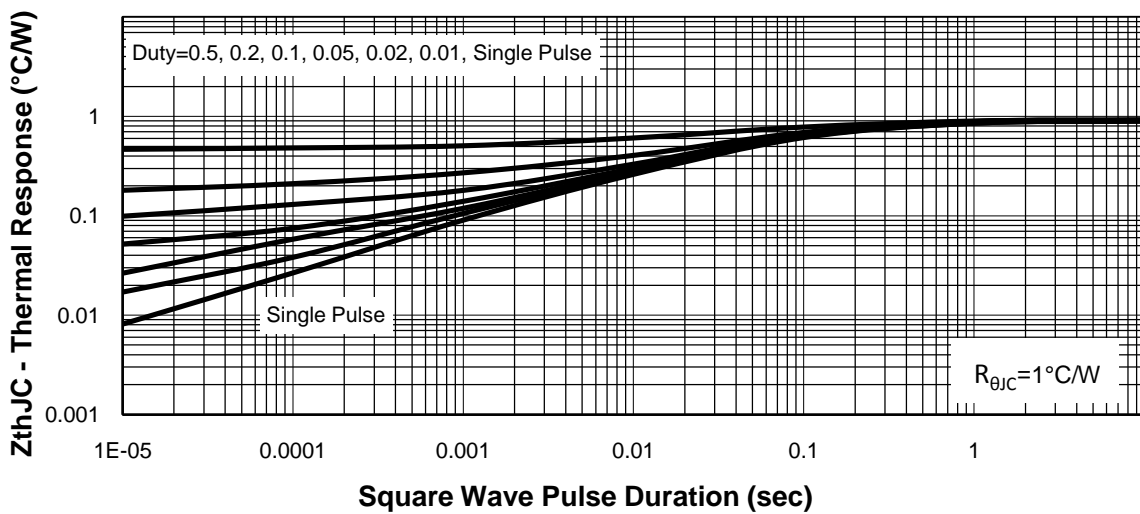
**Ordering and Marking Information**

<b>Device</b>	<b>Marking</b>	<b>Package</b>	<b>Packaging</b>	<b>Quantity</b>	<b>Reel Size</b>	<b>Tape width</b>
RU40120S	RU40120S	TO263	Tube	50	-	-

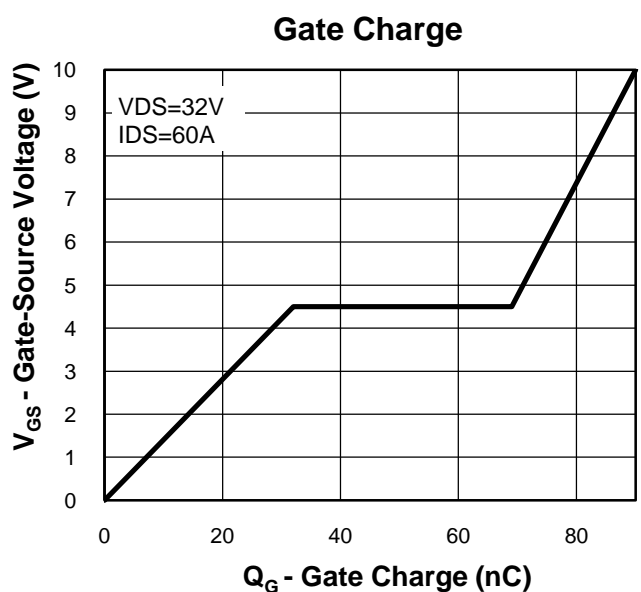
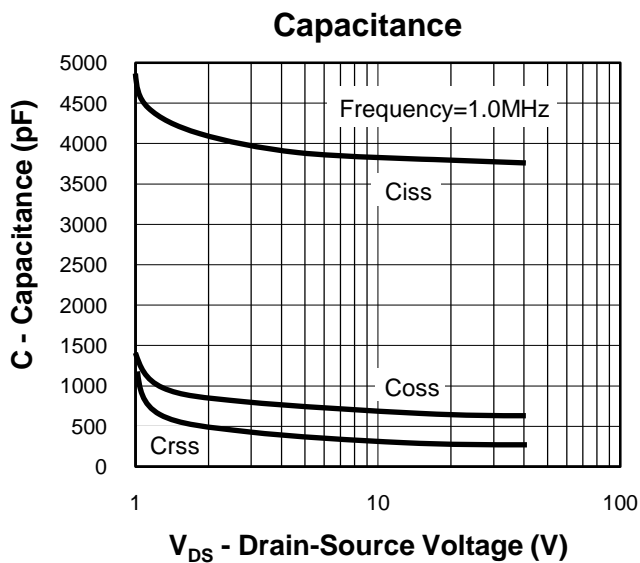
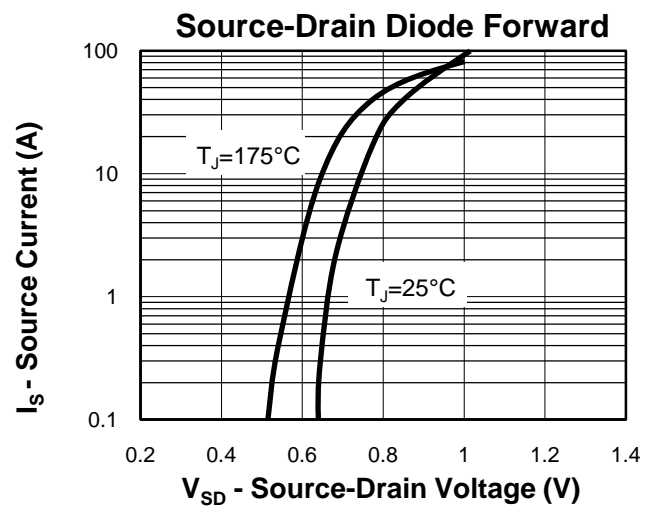
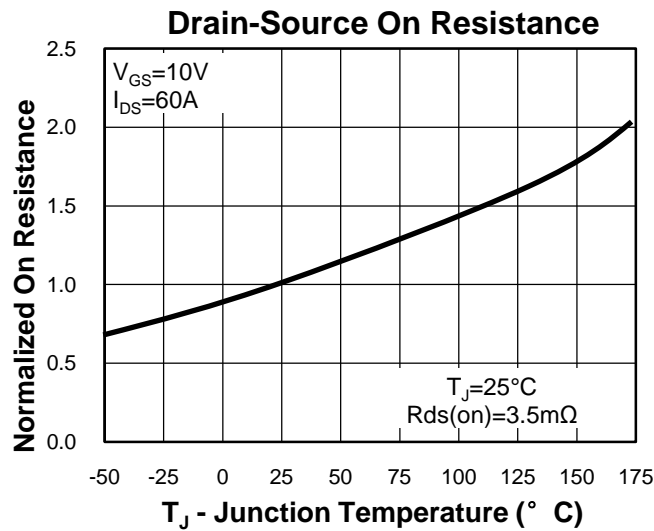
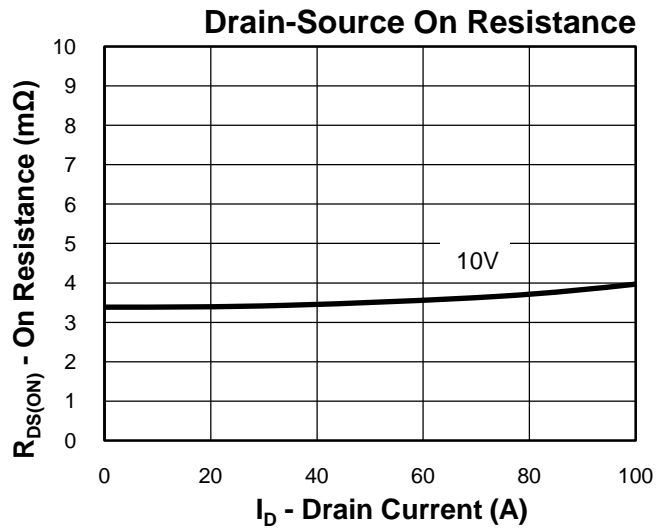
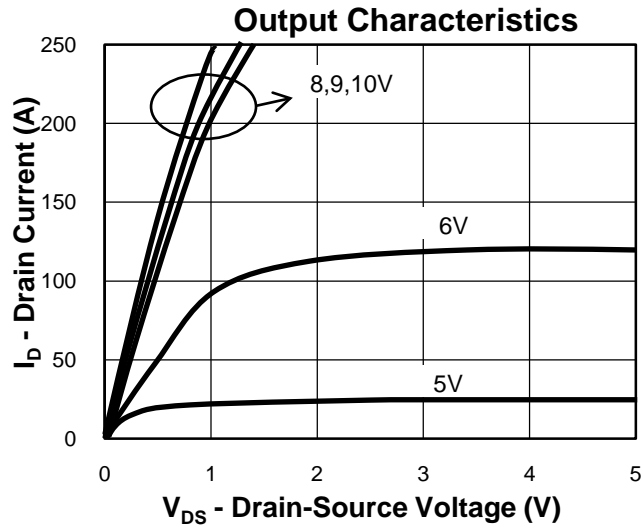
**Typical Characteristics**



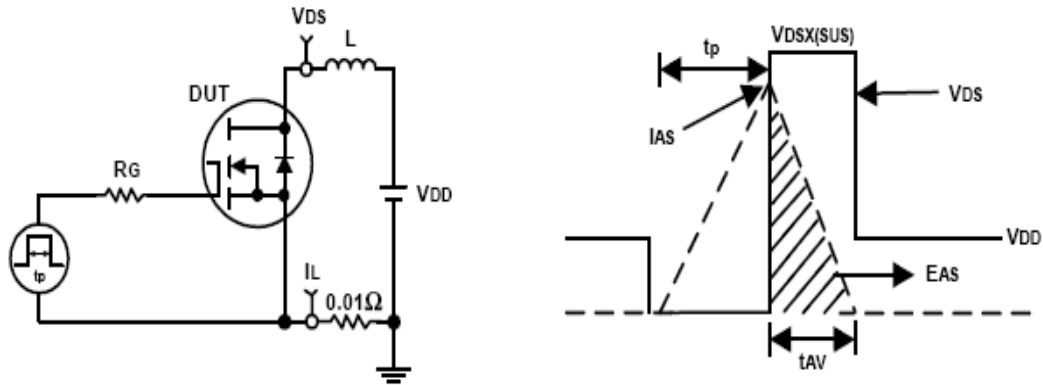
**Thermal Transient Impedance**



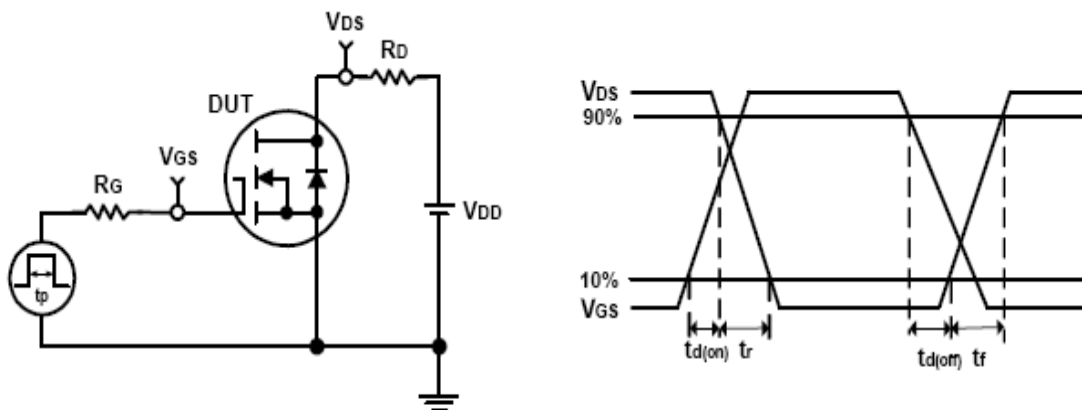
**Typical Characteristics**



**Avalanche Test Circuit and Waveforms**

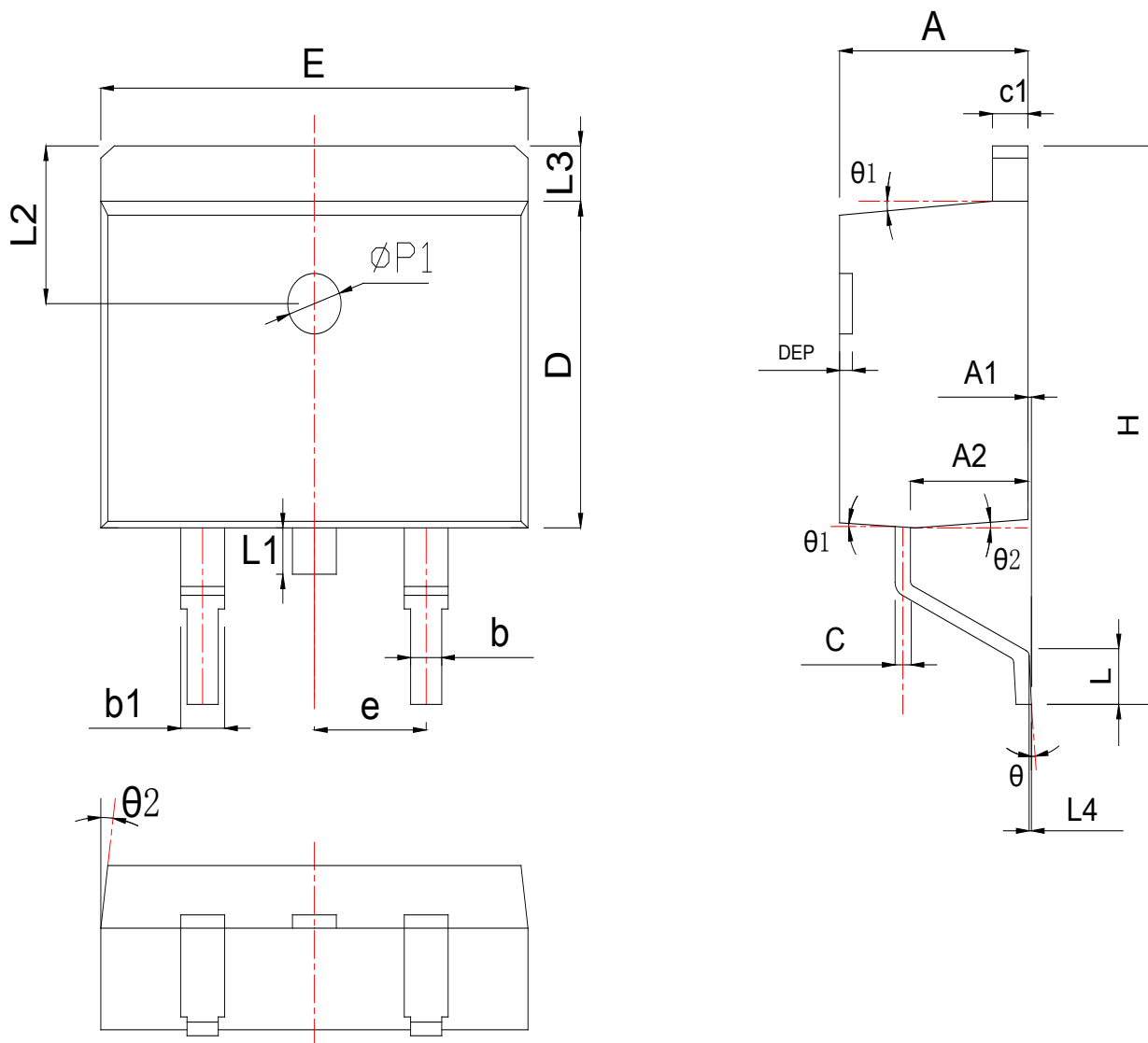


**Switching Time Test Circuit and Waveforms**



**Package Information**

**TO263**



SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.40	4.55	4.70	0.173	0.179	0.185	L	2.00	2.30	2.60	0.079	0.091	0.102
A1	0.00	0.10	0.25	0.000	0.005	0.010	L3	1.17	1.29	1.40	0.046	0.051	0.055
A2	2.59	2.69	2.79	0.102	0.106	0.110	L1	*	*	1.70	*	*	0.067
b	0.77	*	0.90	0.030		0.035	L4	0.25 BSC			0.01 BSC		
b1	1.23	*	1.36	0.048		0.054	L2	2.50 REF			0.098 REF		
c	0.34	*	0.47	0.013		0.019	$\theta$	0°	*	8°	0°	*	8°
c1	1.22	*	1.32	0.048		0.052	$\theta1$	5°	7°	9°	5°	7°	9°
D	8.60	8.70	8.80	0.339	0.343	0.346	$\theta2$	1°	3°	5°	1°	3°	5°
E	10.00	10.13	10.26	0.394	0.399	0.404	DEP	0.05	0.10	0.20	0.002	0.004	0.008
e	2.54BSC			0.100BSC			$\phi p1$	1.40	1.50	1.60	0.055	0.059	0.063
H	14.70	15.10	15.50	0.579	0.594	0.610							

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